

## Multilayer Ceramic Chip Capacitors

# CGA4J1X7R0J106K125AC



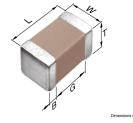






#### **TDK item description** CGA4J1X7R0J106KT\*\*\*\*

| Applications | Automotive Grade                               |  |
|--------------|--|--|
| Feature      | General General (Up to 50V)  AEC-Q200 AEC-Q200 |  |
| Series       | CGA4(2012) [EIA 0805]                          |  |
| Status       | Production                                     |  |



|                                 | Size                               |
|---------------------------------|------------------------------------|
| Length(L)                       | 2.00mm ±0.20mm                     |
| Width(W)                        | 1.25mm ±0.20mm                     |
| Thickness(T)                    | 1.25mm ±0.20mm                     |
| Terminal Width(B)               | 0.20mm Min.                        |
| Terminal Spacing(G)             | 0.50mm Min.                        |
| Recommended Land Pattern (PA)   | 1.00mm to 1.30mm(Flow Soldering)   |
| Neconiniended Land Pattern (PA) | 0.90mm to 1.20mm(Reflow Soldering) |
| Recommended Land Pattern (PB)   | 1.00mm to 1.20mm(Flow Soldering)   |
| Neconiniended Land Fattern (FD) | 0.70mm to 0.90mm(Reflow Soldering) |
| Recommended Land Pattern (PC)   | 0.80mm to 1.10mm(Flow Soldering)   |
| neconfinenced Land Fattern (FC) | 0.90mm to 1.20mm(Reflow Soldering) |

| Electrical Characteristics   |                    |  |
|------------------------------|--------------------|--|
| Capacitance                  | $10\mu F \pm 10\%$ |  |
| Rated Voltage                | 6.3VDC             |  |
| Temperature Characteristic   | X7R(±15%)          |  |
| Dissipation Factor (Max.)    | 10%                |  |
| Insulation Resistance (Min.) | 10ΜΩ               |  |

|                  | Other                                |
|------------------|--------------------------------------|
| Soldering Method | Wave (Flow)                          |
|                  | Reflow                               |
| AEC-Q200         | Yes                                  |
| Packing          | Blister (Plastic)Taping [180mm Reel] |
| Package Quantity | 2000pcs                              |

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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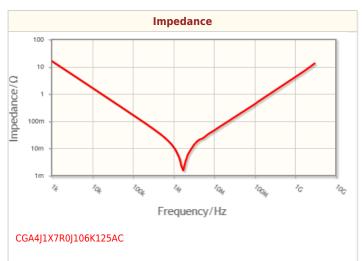


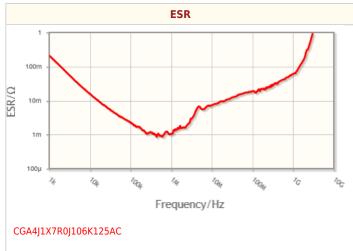


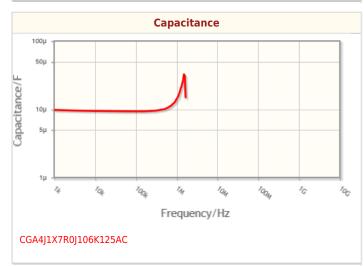


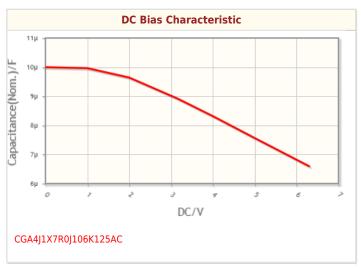


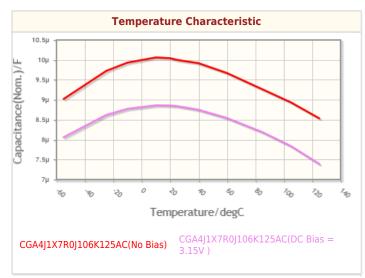
## Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

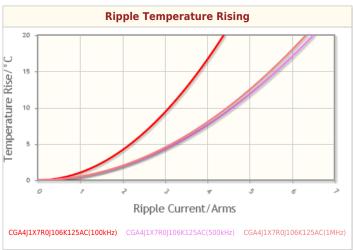












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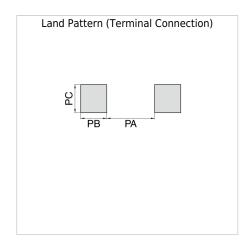








# **Associated Images**



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